

Features

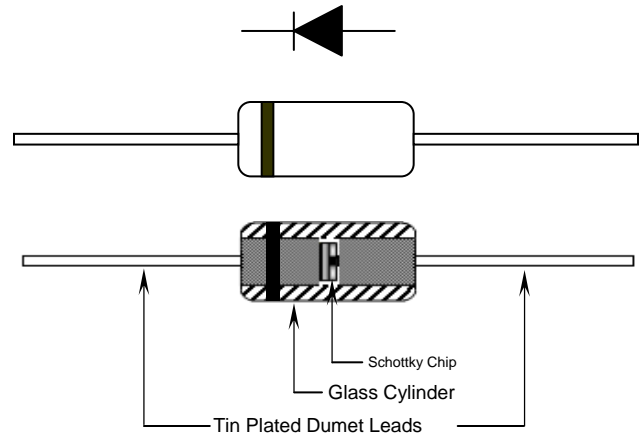
- Low Reverse Leakage Current
- Low Forward Voltage Drop
- Pico second Switching Speed
- Offered in Tape and Reel Packaging
- RoHS Compliant

Description and Applications

These silicon diodes are packaged in a hermetic axial lead glass package. Various uses include detecting, mixing and switching at low power levels. They are suitable for commercial switching along with control functions in narrow band receivers. These diodes can also be used in the UHF and VHF frequency bands for pulse shaping, sampling and as fast logic gates.

Glass Package Style

ODS-54



Ordering Information

Part Number	Package
1N5711	ESD Bag
MADS-005711- 0054MT	Tape and Reel
1N5712	ESD Bag
MADS-005712- 0054MT	Tape and Reel

* Tape and Reel Standard Quantity : 1000 pcs.

Electrical Specifications @ + 25 °C

Parameters and Test Conditions	Symbol	Units	1N5711 MADS-005711-0054MT		1N5712 MADS-005712-0054MT	
			Min.	Max.	Min.	Max.
Forward Voltage @ 1mA	Vf	Volts	-	.410	-	.550
Forward Voltage at @ 15mA	Vf	Volts	-	1	-	-
Forward Voltage at @ 35mA	Vf	Volts	-	-	-	1
Voltage Breakdown @ 10uA	Vb	Volts	70	-	20	-
Leakage Current @ 50 V	Ir	nA	-	200	-	-
Leakage Current @ 15 V	Ir	nA	-	-	-	150
Total Capacitance at 0V at 1 MHz ²	Ct	pF	-	2.0	-	1.2

Notes:

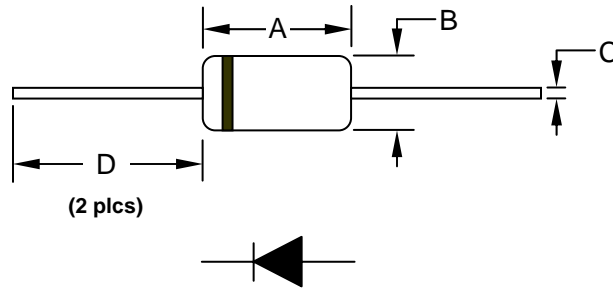
1. Effective minority carrier lifetime (TI) is 100pS maximum measured with the Krakauer method at 5mA.
2. Capacitance is measured at 0 V and 1MHz.

Absolute Maximum Ratings ¹

Parameter	Absolute Maximum
Operating Temperature	-65 °C to +150 °C
Storage Temperature	-65 °C to +200 °C
Reverse Voltage	See voltage ratings.
Power Dissipation	250mW Derate linearly to zero at 135°C
Soldering Temperature	+230°C for 5 seconds 1mm from glass
Electrostatic Discharge (ESD) Classification ²	Class 0

1. Operation of this device above any one of these parameters may cause permanent damage.
2. Human Body Model

Package Outline Dimensions



Package Style	Dimension A		Dimension B		Dimension C		Dimension D (Min.)	
	Mils	mm	Mils	mm	Mils	mm	Mils	mm
54	155 ± 10	3.94 ± .25	71 ± 3	1.8 ± .08	15 ± 1	.38 ± .03	1000	25.4

Assembly Recommendations

- Leads on axial leaded devices must be formed while being held firm. Bending the leads too close to the body of the part may cause internal damage to the device. Bends <0.060" from body are not recommended. Appropriate fixturing should be used.
- Devices may be soldered using standard 60/40, Sn/Pb or RoHS compliant solders. Axial leads are tin plated, 50µM, thick to ensure an optimum connection.